

## Initial Product/Process Change Notification Document #:IPCN21092X

Issue Date: 25 November 2015

Title of Change:	Copper wire conversion and mold compound change for LA74330V.		
Proposed first ship date:	6 June 2016		
Contact information:	Contact your local ON Semiconductor Sales Office or <a href="Ikuo.Osawa@onsemi.com"><a href="Ikuo.Osawa@onsemi.com"></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a></a>		

Estimated date for qualification completion: 12 February 2016

Package name: SSOP030 (V4B90)

Test	Specification	Condition	Interval
HTOL	JESD22-A108	Tj=Tjmax, , Vcc=Operatingmax	1008 hrs
THB	JESD22-A101	85°C, 85% RH, Vcc=Operatingmax	1008 hrs
HTS	JESD22-A104	Ta= 150°C	1008 hrs
TC	JESD22-A104	Ta= -65°C to +150°C	500 cyc
AC	JESD22-A102	Ta=121degC,15psig	96 hrs
PC	J-STD-020 JESD-A113	MSL 3 @ 260 °C	

The test items with \* mark are put into operation after the reflow soldering (at 255degC for 10seconds) -> SMD Temperature Humidity Bias Test: PD>=0.1W -> Intermittent power application consists of 1h ON and 3h OFF.

Judgment Criteria:

Judgment Criteria are due to the limits of the electrical characteristics in the detail specification

TEM001091 Rev. E Page 1 of 2



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List of Affected Standard Parts:			
Part Number	Qualification Vehicle		
LA74330V-TLM-H	LA74330V-TLM-H		

TEM001091 Rev. E Page 2 of 2